

LCC

Leadless Chip Carrier Package (LCC)

Amkor Technology is committed to continuing to service this long established standard industry package. This surface mount package consists of a co-fired ceramic base that has metalized terminals / pads on the sides and bottom of the package. An LCC package has terminals / pads on all four edges of the package. The lid for this package can be either ceramic "frit sealed" or metal "solder sealed". This package provides a hermetic environment for the IC inside.

Applications:

This IC package technology allows application and design engineers to maximize the performance characteristics of semiconductors (silicon, GaAs and S.A.W.). These packages enable end products (pagers, portable audio/video, disc drives, radio, IF & RF devices/components, telecom) to be reduced in size and weight. Semiconductor families such as operational amplifiers, drivers, optoelectronics, controllers, logic, analog, memory, comparators and more using BiCMOS, CMOS or other silicon/GaAs/S.A.W. technologies are well addressed by the LCC product family.

Features:

The LCC offers a variety of features. From standard industry, Amkor provides a platform from prototype-to-production:

- Flexible lead / pin counts
- Variety of body sizes
- Hermetic package
- Exceptional thermal and electrical performance by design
- Multi-layer, ground / power
- Cavity Up / Cavity down configurations
- Cavity package

